

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



BASIC EMC PUBLICATION

PUBLICATION FONDAMENTALE EN CEM

**Electromagnetic compatibility (EMC) –  
Part 4-6: Testing and measurement techniques – Immunity to conducted  
disturbances, induced by radio-frequency fields**

**Compatibilité électromagnétique (CEM) –  
Partie 4-6: Techniques d'essai et de mesure – Immunité aux perturbations  
conduites, induites par les champs radioélectriques**



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Edition 4.0 2013-10

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTROMAGNETIC COMPATIBILITY (EMC) –****Part 4-6: Testing and measurement techniques –  
Immunity to conducted disturbances,  
induced by radio-frequency fields**

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International Standard IEC 61000-4-6 has been prepared by subcommittee 77B: High frequency phenomena, of IEC technical committee 77: Electromagnetic compatibility.

It forms Part 4-6 of IEC 61000. It has the status of a basic EMC publication in accordance with IEC Guide 107.

This fourth edition cancels and replaces the third edition published in 2008 and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) use of the CDNs;
- b) calibration of the clamps;
- c) reorganization of Clause 7 on test setup and injection methods;

- d) Annex A which is now dedicated to EM and decoupling clamps;
- e) Annex G which now addresses the measurement uncertainty of the voltage test level;
- f) informative Annexes H, I and J which are new.

The text of this standard is based on the following documents:

FDIS	Report on voting
77B/691/FDIS	77B/704/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61000 series, published under the general title *Electromagnetic compatibility (EMC)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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The contents of the corrigendum of June 2015 have been included in this copy.

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## INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

### **Part 1: General**

General considerations (introduction, fundamental principles)

Definitions, terminology

### **Part 2: Environment**

Description of the environment

Classification of the environment

Compatibility levels

### **Part 3: Limits**

Emission limits

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

### **Part 4: Testing and measurement techniques**

Measurement techniques

Testing techniques

### **Part 5: Installation and mitigation guidelines**

Installation guidelines

Mitigation methods and devices

[IEC 61000-4-6:2013](#)

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### **Part 6: Generic standards**

### **Part 9: Miscellaneous**

Each part is further subdivided into several parts, published either as international standards or as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number identifying the subdivision (example: IEC 61000-6-1).

This part is an international standard which gives immunity requirements and test procedures related to conducted disturbances induced by radio-frequency fields.

## ELECTROMAGNETIC COMPATIBILITY (EMC) –

### Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields

#### 1 Scope

This part of IEC 61000 relates to the conducted immunity requirements of electrical and electronic equipment to electromagnetic disturbances coming from intended radio-frequency (RF) transmitters in the frequency range 150 kHz up to 80 MHz. Equipment not having at least one conducting wire and/or cable (such as mains supply, signal line or earth connection) which can couple the equipment to the disturbing RF fields is excluded from the scope of this publication.

NOTE 1 Test methods are defined in this part of IEC 61000 to assess the effect that conducted disturbing signals, induced by electromagnetic radiation, have on the equipment concerned. The simulation and measurement of these conducted disturbances are not adequately exact for the quantitative determination of effects. The test methods defined are structured for the primary objective of establishing adequate repeatability of results at various facilities for quantitative analysis of effects.

The object of this standard is to establish a common reference for evaluating the functional immunity of electrical and electronic equipment when subjected to conducted disturbances induced by RF fields. The test method documented in this part of IEC 61000 describes a consistent method to assess the immunity of an equipment or system against a defined phenomenon.

IEC 61000-4-6:2013

NOTE 2 As described in IEC Guide 107, this standard is a basic EMC publication for use by product committees of the IEC. As also stated in Guide 107, the IEC product committees are responsible for determining whether this immunity test standard should be applied or not, and if applied, they are responsible for determining the appropriate test levels and performance criteria.

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary (IEV)* (available at <http://www.electropedia.org>)

#### 3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60050-161 as well as the following apply.

##### 3.1

##### **artificial hand**

electrical network simulating the impedance of the human body under average operational conditions between a hand-held electrical appliance and earth

Note 1 to entry: The construction should be in accordance with CISPR 16-1-2.

[SOURCE: IEC 60050-161:1990, 161-04-27]

## 3.2

**auxiliary equipment****AE**

equipment necessary to provide the equipment under test (EUT) with the signals required for normal operation and equipment to verify the performance of the EUT

## 3.3

**clamp injection**

clamp injection is obtained by means of a clamp-on “current” injecting device on the cable

## 3.4

**clamp injection device**

clamp-on “current” injecting device on a cable being either a current clamp or an electromagnetic clamp

## 3.4.1

**current clamp**

transformer, the secondary winding of which consists of the cable into which the injection is made

## 3.4.2

**electromagnetic clamp****EM clamp**

injection device with combined capacitive and inductive coupling

## 3.5

**common mode impedance** (standards.iteh.ai)

ratio of the common mode voltage and the common mode current at a certain port

[IEC 61000-4-6:2013](#)

Note 1 to entry: This common mode impedance can be determined by applying a unity common mode voltage between the terminal(s) or screen of that port and a reference plane (point). The resulting common mode current is then measured as the vectorial sum of all currents flowing through these terminal(s) or screen (see also Figures 8a) and 8b)).

## 3.6

**coupling factor**

ratio given by the open-circuit voltage (e.m.f.) obtained at the EUT port of the coupling (and decoupling) device divided by the open-circuit voltage obtained at the output of the test generator

## 3.7

**coupling network**

electrical circuit for transferring energy from one circuit to another with a defined impedance

Note 1 to entry: Coupling and decoupling devices can be integrated into one box (coupling and decoupling network (CDN)) or they can be in separate networks.

## 3.8

**coupling/decoupling network****CDN**

electrical circuit incorporating the functions of both the coupling and decoupling networks

## 3.9

**decoupling network****decoupling device**

electrical circuit for preventing test signals applied to the EUT from affecting other devices, equipment or systems that are not under test

## 3.10

**test generator**

generator (RF generator, modulation source, attenuators, broadband power amplifier and filters) capable of generating the required test signal

Note 1 to entry: See Figure 3.

## 3.11

**electromotive force****e.m.f.**

voltage at the terminals of the ideal voltage source in the representation of an active element

## 3.12

**measurement result** $U_{mr}$ 

voltage reading of the measurement equipment

## 3.13

**voltage standing wave ratio****VSWR**

ratio of a maximum to an adjacent minimum voltage magnitude along the line

**4 General**

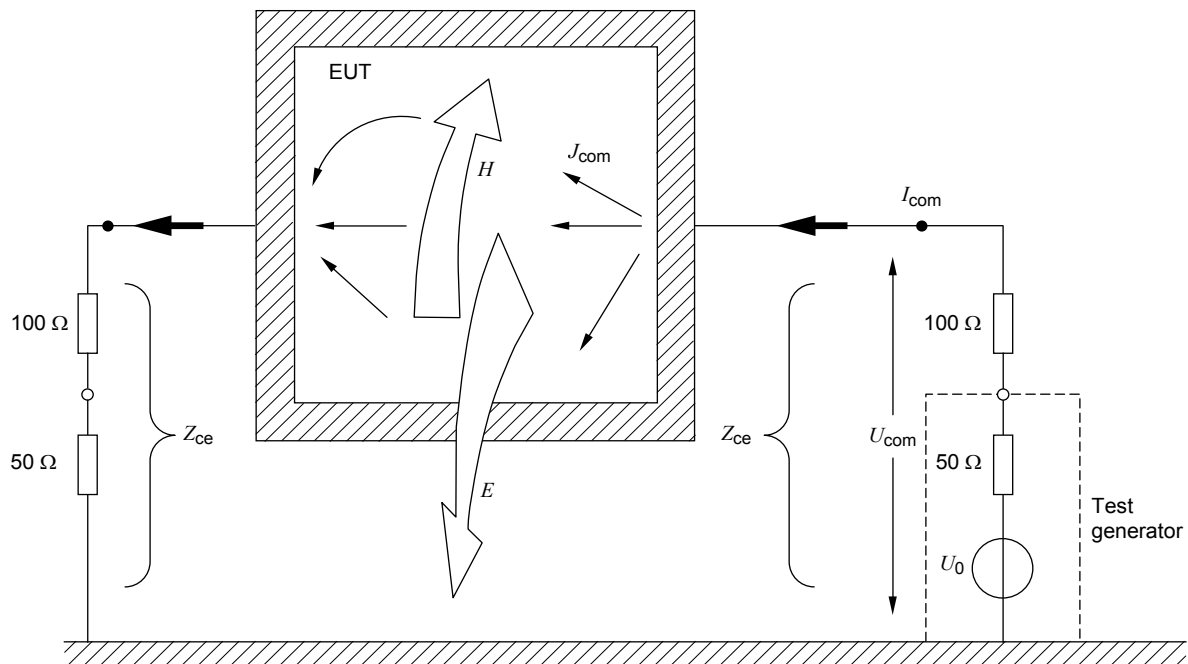
The source of disturbance covered by this part of IEC 61000 is basically an electromagnetic field, coming from intended RF transmitters, that may act on the whole length of cables connected to installed equipment. The dimensions of the disturbed equipment, mostly a sub-part of a larger system, are assumed to be small compared with the wavelengths of the interfering signals. The leads entering and exiting the EUT (e.g. mains, communication lines, interface cables) behave as passive receiving antenna networks and signal conduction paths for both intentional and unintentional signals. Standard (S.J.P.) (S) iTeh STANDARD PREVIEW (see www.it-ebooks.info) /cc/by-nc/3.0/iec-61000-4-6-2013

Between those cable networks, the susceptible equipment is exposed to currents flowing "through" the equipment. Cable systems connected to an equipment are assumed to be in resonant mode ( $\lambda/4$ ,  $\lambda/2$  open or folded dipoles) and as such are represented by coupling and decoupling devices having a common mode impedance of  $150 \Omega$  with respect to a reference ground plane. Where possible the EUT is tested by connecting it between two  $150 \Omega$  common mode impedance connections: one providing an RF source and the other providing a return path for the current.

This test method subjects the EUT to a source of disturbance comprising electric and magnetic fields, simulating those coming from intentional RF transmitters. These disturbing fields (E and H) are approximated by the electric and magnetic near-fields resulting from the voltages and currents caused by the test setup as shown in Figure 1a).

The use of coupling and decoupling devices to apply the disturbing signal to one cable at a time, while keeping all other cables nonexcited (see Figure 1b)), can only approximate the real situation where disturbing sources act on all cables simultaneously, with a range of different amplitudes and phases.

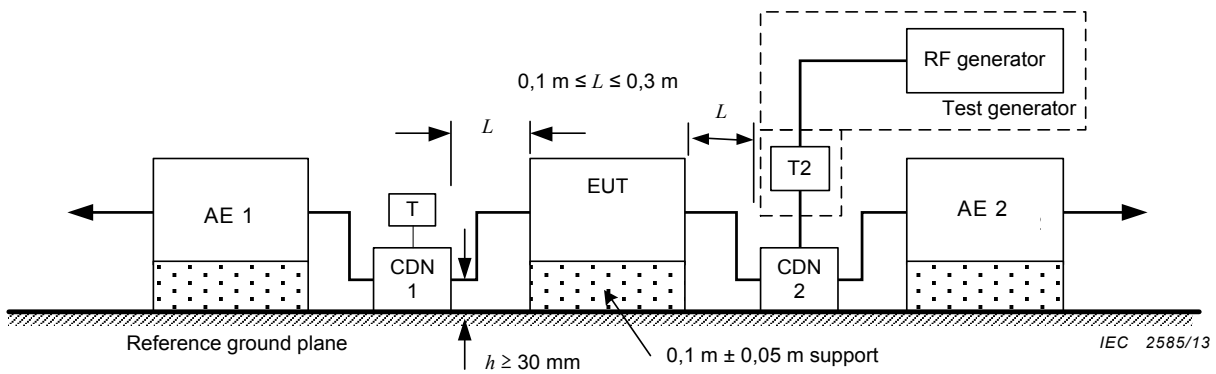
Coupling and decoupling devices are defined by their characteristics given in 6.2.1. Any coupling and decoupling device fulfilling these characteristics can be used. The CDNs in Annex D are only examples of commercially available networks.



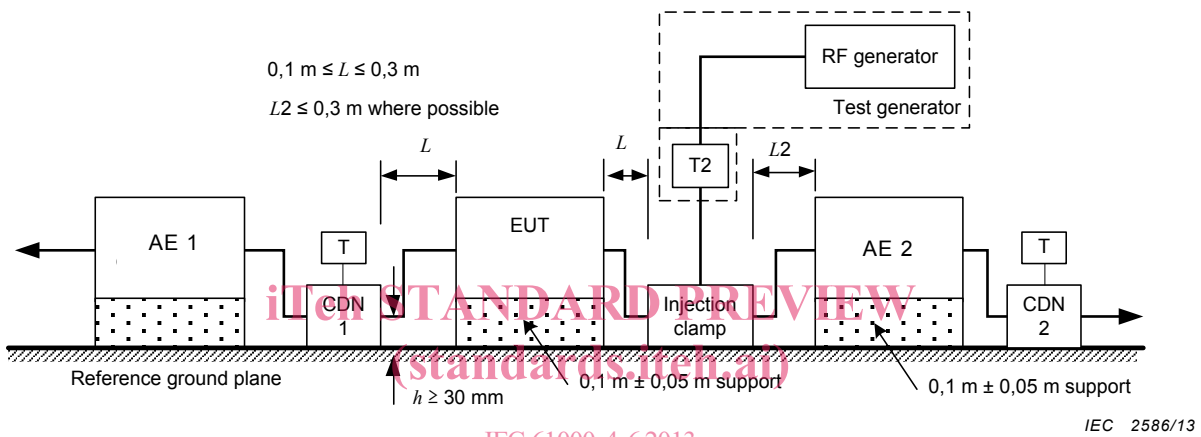
$Z_{ce}$	Common mode impedance of the CDN system, $Z_{ce} = 150 \Omega$
$U_0$	Test generator source voltage (e.m.f.)
$U_{com}$	Common mode voltage between EUT and reference plane
$I_{com}$	Common mode current through the EUT
$J_{com}$	Current density on conducting surface or current on other conductors of the EUT
$E, H$	Electric and magnetic fields

NOTE The  $100 \Omega$  resistors are included in the CDNs. The left input is loaded by a (passive)  $50 \Omega$  load and the right input is loaded by the source impedance of the test generator.

**a) Diagram showing EM fields near the EUT due to common mode currents on its cables**



Schematic setup for immunity test used for CDN



Schematic setup for immunity test used for injection clamp

- T Termination 50 Ω
- T2 Power attenuator (6 dB)
- CDN Coupling and decoupling network
- Injection clamp: Current clamp or EM clamp

b) Schematic setup for immunity test to RF conducted disturbances

Figure 1 – Immunity test to RF conducted disturbances

5 Test levels

According to this standard, tests are required for induced disturbances caused by electromagnetic fields coming from intentional RF transmitters in the frequency range 150 kHz to 80 MHz.

The open circuit test levels (e.m.f.) of the unmodulated disturbing signal, expressed in r.m.s., are given in Table 1.

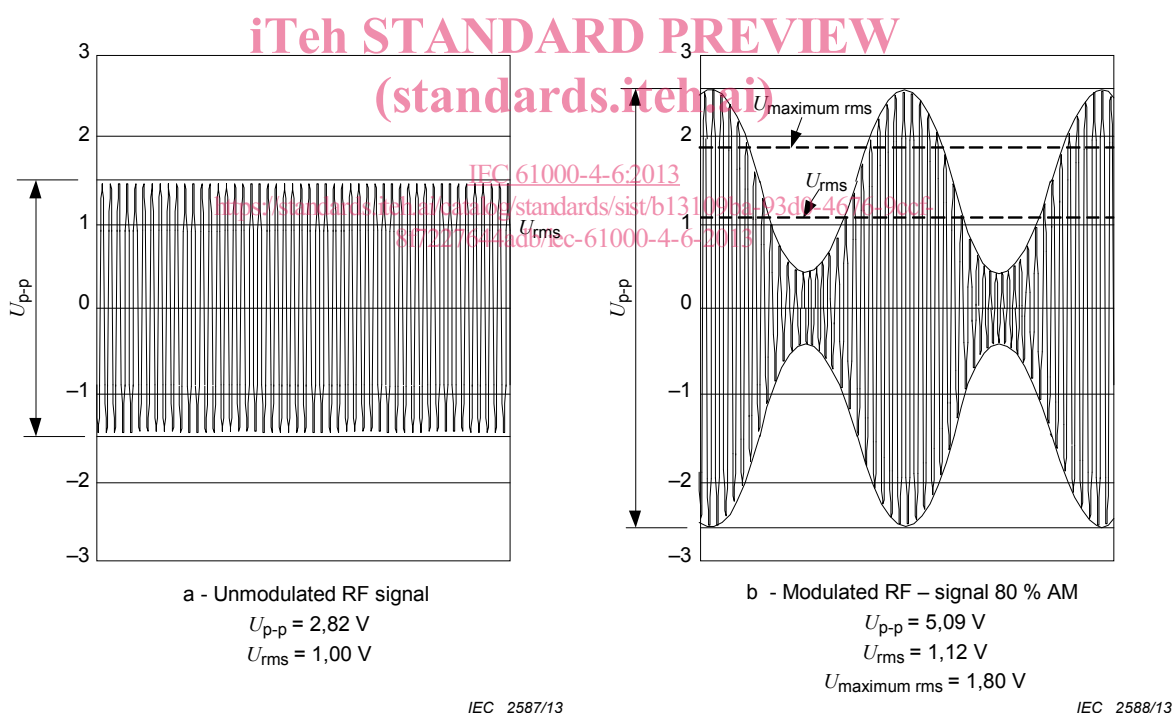
**Table 1 – Test levels**

Frequency range 150 kHz to 80 MHz		
Level	Voltage level (e.m.f.)	
	$U_0$ V	$U_0$ dB( $\mu$ V)
1	1	120
2	3	129,5
3	10	140
X <sup>a</sup>	Special	
<sup>a</sup> "X" can be any level, above, below or in between the others. The level has to be specified in the dedicated equipment specification.		

The test levels are set at the EUT port of the coupling devices, see 6.4. For testing of the equipment, this signal is 80 % amplitude modulated with a 1 kHz sine wave to simulate actual threats. The effective amplitude modulation is shown in Figure 2. Guidance for selecting test levels is given in Annex C.

NOTE 1 IEC 61000-4-3 also defines test methods for establishing the immunity of electrical and electronic equipment against radiated electromagnetic energy. It covers frequencies above 80 MHz. Product committees can decide to choose a lower or higher transition frequency than 80 MHz (see Annex B).

NOTE 2 Product committees can select alternative modulation schemes.



**Figure 2 – Open circuit waveforms at the EUT port of a coupling device for test level 1**

## 6 Test equipment and level adjustment procedures

### 6.1 Test generator

The test generator includes all equipment and components for supplying the input port of each coupling device with the disturbing signal at the required signal level at the appropriate injection point. A typical arrangement comprises the following items which may be separate or integrated into one or more test instruments (see 3.10 and Figure 3):